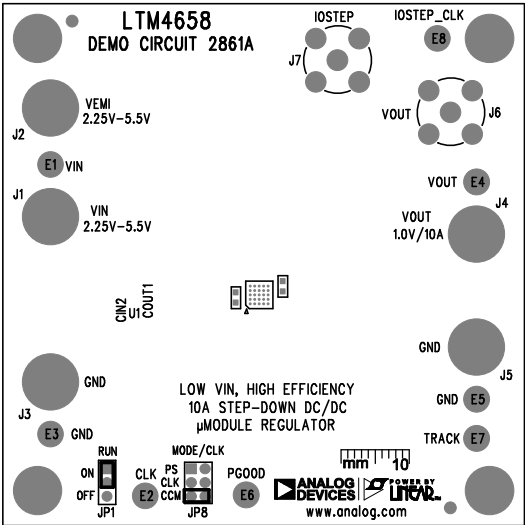
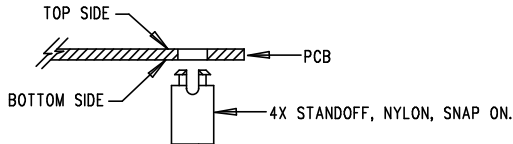




REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	3	PROTOTYPE	YL	01-17-20



**NOTES: UNLESS OTHERWISE SPECIFIED**

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL STANDOFFS AS SHOWN BELOW:



<b>APPROVALS</b>		 	
PCB DES.	LT	<b>TITLE: ASSEMBLY DRAWING, TOP</b> LOW VIN, HIGH EFFICIENCY 10A STEP-DOWN DC/DC $\mu$ MODULE REGULATOR	
APP ENG.	YAN L.		
SCALE = NONE		SIZE N/A	IC NO. LTM4658EY DEMO CIRCUIT 2861A
FILENAME: DC2861A-3.PCB		REV 3	
		SHT 1 OF 2	